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### What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

### Applications of "[Embedded - Microcontrollers](#)"

#### Details

Product Status	Active
Core Processor	ARM® Cortex®-M0+
Core Size	32-Bit Single-Core
Speed	24MHz
Connectivity	I <sup>2</sup> C, IrDA, LINbus, Microwire, SmartCard, SPI, SSP, UART/USART
Peripherals	Brown-out Detect/Reset, CapSense, LCD, LVD, POR, PWM, WDT
Number of I/O	27
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	1.71V ~ 5.5V
Data Converters	A/D 16x10b Slope, 16x12b SAR; D/A 2xIDAC
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	32-UFQFN Exposed Pad
Supplier Device Package	32-QFN (5x5)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/infineon-technologies/cy8c4125lqi-s422t">https://www.e-xfl.com/product-detail/infineon-technologies/cy8c4125lqi-s422t</a>

## Reset

The PSoC 4100S can be reset from a variety of sources including a software reset. Reset events are asynchronous and guarantee reversion to a known state. The reset cause is recorded in a register, which is sticky through reset and allows software to determine the cause of the reset. An XRES pin is reserved for external reset by asserting it active low. The XRES pin has an internal pull-up resistor that is always enabled.

## Analog Blocks

### 12-bit SAR ADC

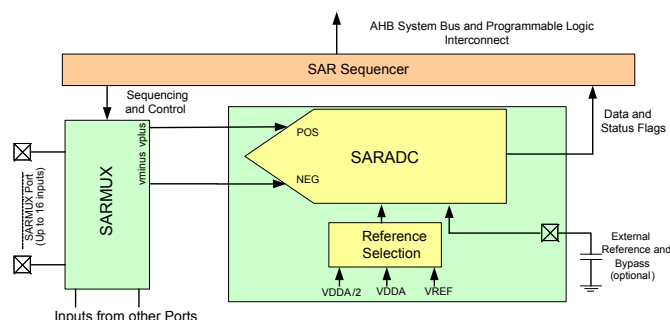
The 12-bit, 1-Msps SAR ADC can operate at a maximum clock rate of 18 MHz and requires a minimum of 18 clocks at that frequency to do a 12-bit conversion.

The Sample-and-Hold (S/H) aperture is programmable allowing the gain bandwidth requirements of the amplifier driving the SAR inputs, which determine its settling time, to be relaxed if required. It is possible to provide an external bypass (through a fixed pin location) for the internal reference amplifier.

The SAR is connected to a fixed set of pins through an 8-input sequencer. The sequencer cycles through selected channels autonomously (sequencer scan) with zero switching overhead (that is, aggregate sampling bandwidth is equal to 1 Msps whether it is for a single channel or distributed over several channels). The sequencer switching is effected through a state machine or through firmware driven switching. A feature provided by the sequencer is buffering of each channel to reduce CPU interrupt service requirements. To accommodate signals with varying source impedance and frequency, it is possible to have different sample times programmable for each channel. Also, signal range specification through a pair of range registers (low and high range values) is implemented with a corresponding out-of-range interrupt if the digitized value exceeds the programmed range; this allows fast detection of out-of-range values without the necessity of having to wait for a sequencer scan to be completed and the CPU to read the values and check for out-of-range values in software.

The SAR is not available in Deep Sleep mode as it requires a high-speed clock (up to 18 MHz). The SAR operating range is 1.71 V to 5.5 V.

**Figure 3. SAR ADC**



### Two Opamps (Continuous-Time Block; CTB)

The PSoC 4100S has two opamps with Comparator modes which allow most common analog functions to be performed on-chip eliminating external components; PGAs, Voltage

Buffers, Filters, Trans-Impedance Amplifiers, and other functions can be realized, in some cases with external passives, saving power, cost, and space. The on-chip opamps are designed with enough bandwidth to drive the Sample-and-Hold circuit of the ADC without requiring external buffering.

### Low-power Comparators (LPC)

The PSoC 4100S has a pair of low-power comparators, which can also operate in Deep Sleep modes. This allows the analog system blocks to be disabled while retaining the ability to monitor external voltage levels during low-power modes. The comparator outputs are normally synchronized to avoid metastability unless operating in an asynchronous power mode where the system wake-up circuit is activated by a comparator switch event. The LPC outputs can be routed to pins.

### Current DACs

The PSoC 4100S has two IDACs, which can drive any of the pins on the chip. These IDACs have programmable current ranges.

### Analog Multiplexed Buses

The PSoC 4100S has two concentric independent buses that go around the periphery of the chip. These buses (called amux buses) are connected to firmware-programmable analog switches that allow the chip's internal resources (IDACs, comparator) to connect to any pin on the I/O Ports.

## Programmable Digital Blocks

The Programmable I/O (Smart I/O) block is a fabric of switches and LUTs that allows Boolean functions to be performed in signals being routed to the pins of a GPIO port. The Smart I/O can perform logical operations on input pins to the chip and on signals going out as outputs.

## Fixed Function Digital

### Timer/Counter/PWM (TCPWM) Block

The TCPWM block consists of a 16-bit counter with user-programmable period length. There is a capture register to record the count value at the time of an event (which may be an I/O event), a period register that is used to either stop or auto-reload the counter when its count is equal to the period register, and compare registers to generate compare value signals that are used as PWM duty cycle outputs. The block also provides true and complementary outputs with programmable offset between them to allow use as dead-band programmable complementary PWM outputs. It also has a Kill input to force outputs to a predetermined state; for example, this is used in motor drive systems when an over-current state is indicated and the PWM driving the FETs needs to be shut off immediately with no time for software intervention. There are five TCPWM blocks in the PSoC 4100S.

### Serial Communication Block (SCB)

The PSoC 4100S has three serial communication blocks, which can be programmed to have SPI, I2C, or UART functionality.

**I<sup>2</sup>C Mode:** The hardware I<sup>2</sup>C block implements a full multi-master and slave interface (it is capable of multi-master arbitration). This block is capable of operating at speeds of up to 400 kbps (Fast Mode) and has flexible buffering options to reduce interrupt overhead and latency for the CPU. It also

supports EZI2C that creates a mailbox address range in the memory of the PSoC 4100S and effectively reduces I<sup>2</sup>C communication to reading from and writing to an array in memory. In addition, the block supports an 8-deep FIFO for receive and transmit which, by increasing the time given for the CPU to read data, greatly reduces the need for clock stretching caused by the CPU not having read data on time.

The I<sup>2</sup>C peripheral is compatible with the I<sup>2</sup>C Standard-mode and Fast-mode devices as defined in the NXP I<sup>2</sup>C-bus specification and user manual (UM10204). The I<sup>2</sup>C bus I/O is implemented with GPIO in open-drain modes.

The PSoC 4100S is not completely compliant with the I<sup>2</sup>C spec in the following respect:

- GPIO cells are not overvoltage tolerant and, therefore, cannot be hot-swapped or powered up independently of the rest of the I<sup>2</sup>C system.

**UART Mode:** This is a full-feature UART operating at up to 1 Mbps. It supports automotive single-wire interface (LIN), infrared interface (IrDA), and SmartCard (ISO7816) protocols, all of which are minor variants of the basic UART protocol. In addition, it supports the 9-bit multiprocessor mode that allows addressing of peripherals connected over common RX and TX lines. Common UART functions such as parity error, break detect, and frame error are supported. An 8-deep FIFO allows much greater CPU service latencies to be tolerated.

**SPI Mode:** The SPI mode supports full Motorola SPI, TI SSP (adds a start pulse used to synchronize SPI Codecs), and National Microwire (half-duplex form of SPI). The SPI block can use the FIFO.

## GPIO

The PSoC 4100S has up to 36 GPIOs. The GPIO block implements the following:

- Eight drive modes:
  - Analog input mode (input and output buffers disabled)
  - Input only
  - Weak pull-up with strong pull-down
  - Strong pull-up with weak pull-down
  - Open drain with strong pull-down
  - Open drain with strong pull-up
  - Strong pull-up with strong pull-down
  - Weak pull-up with weak pull-down
- Input threshold select (CMOS or LVTTL).
- Individual control of input and output buffer enabling/disabling in addition to the drive strength modes
- Selectable slew rates for dV/dt related noise control to improve EMI

The pins are organized in logical entities called ports, which are 8-bit in width (less for Ports 2 and 3). During power-on and reset, the blocks are forced to the disable state so as not to crowbar any inputs and/or cause excess turn-on current. A multiplexing network known as a high-speed I/O matrix is used to multiplex between various signals that may connect to an I/O pin.

Data output and pin state registers store, respectively, the values to be driven on the pins and the states of the pins themselves.

Every I/O pin can generate an interrupt if so enabled and each I/O port has an interrupt request (IRQ) and interrupt service routine (ISR) vector associated with it (5 for PSoC 4100S).

## Special Function Peripherals

### CapSense

CapSense is supported in the PSoC 4100S through a CapSense Sigma-Delta (CSD) block that can be connected to any pins through an analog multiplex bus via analog switches. CapSense function can thus be provided on any available pin or group of pins in a system under software control. A PSoC Creator component is provided for the CapSense block to make it easy for the user.

Shield voltage can be driven on another analog multiplex bus to provide water-tolerance capability. Water tolerance is provided by driving the shield electrode in phase with the sense electrode to keep the shield capacitance from attenuating the sensed input. Proximity sensing can also be implemented.

The CapSense block has two IDACs, which can be used for general purposes if CapSense is not being used (both IDACs are available in that case) or if CapSense is used without water tolerance (one IDAC is available).

The CapSense block also provides a 10-bit Slope ADC function which can be used in conjunction with the CapSense function.

The CapSense block is an advanced, low-noise, programmable block with programmable voltage references and current source ranges for improved sensitivity and flexibility. It can also use an external reference voltage. It has a full-wave CSD mode that alternates sensing to VDDA and ground to null out power-supply related noise.

### LCD Segment Drive

The PSoC 4100S has an LCD controller, which can drive up to 4 commons and up to 32 segments. It uses full digital methods to drive the LCD segments requiring no generation of internal LCD voltages. The two methods used are referred to as Digital Correlation and PWM. Digital Correlation pertains to modulating the frequency and drive levels of the common and segment signals to generate the highest RMS voltage across a segment to light it up or to keep the RMS signal to zero. This method is good for STN displays but may result in reduced contrast with TN (cheaper) displays. PWM pertains to driving the panel with PWM signals to effectively use the capacitance of the panel to provide the integration of the modulated pulse-width to generate the desired LCD voltage. This method results in higher power consumption but can result in better results when driving TN displays. LCD operation is supported during Deep Sleep refreshing a small display buffer (4 bits; 1 32-bit register per port).

**Table 1. Pin List** (continued)

48-TQFP		44-TQFP		40-QFN		32-QFN		35-CSP	
Pin	Name	Pin	Name	Pin	Name	Pin	Name	Pin	Name
19	P3.6	17	P3.6	16	P3.6				
20	P3.7	18	P3.7	17	P3.7				
21	VDDD	19	VDDD						
22	P4.0	20	P4.0	18	P4.0	13	P4.0	B1	P4.0
23	P4.1	21	P4.1	19	P4.1	14	P4.1	B2	P4.1
24	P4.2	22	P4.2	20	P4.2	15	P4.2	A2	P4.2
25	P4.3	23	P4.3	21	P4.3	16	P4.3	A1	P4.3

**Notes:** Pins 11, 15, 26, and 27 are No Connects (NC) on the 48-pin TQFP.

**Descriptions of the Power pins are as follows:**

VDDD: Power supply for the digital section.

VDDA: Power supply for the analog section.

VSSD, VSSA: Ground pins for the digital and analog sections respectively.

VCCD: Regulated digital supply (1.8 V  $\pm$ 5%)

VDD: Power supply to all sections of the chip

VSS: Ground for all sections of the chip

## Alternate Pin Functions

Each Port pin has can be assigned to one of multiple functions; it can, for instance, be an analog I/O, a digital peripheral function, an LCD pin, or a CapSense pin. The pin assignments are shown in the following table.

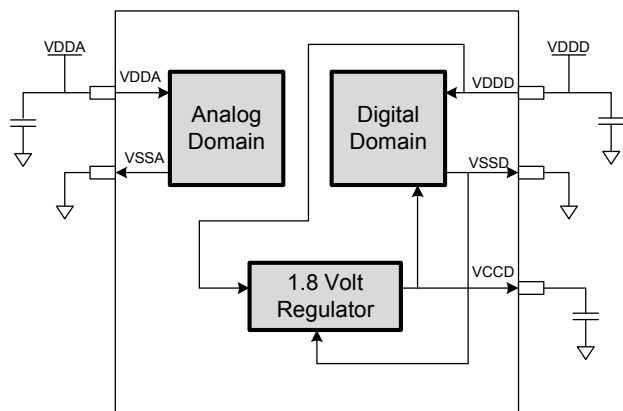
Port/Pin	Analog	Smart I/O	Alternate Function 1	Alternate Function 2	Alternate Function 3	Deep Sleep 1	Deep Sleep 2
P0.0	lpcomp.in_p[0]				tcpwm.tr_in[0]	scb[2].i2c_scl:0	scb[0].spi_select1:0
P0.1	lpcomp.in_n[0]				tcpwm.tr_in[1]	scb[2].i2c_sda:0	scb[0].spi_select2:0
P0.2	lpcomp.in_p[1]						scb[0].spi_select3:0
P0.3	lpcomp.in_n[1]						scb[2].spi_select0
P0.4	wco.wco_in			scb[1].uart_rx:0	scb[2].uart_rx:0	scb[1].i2c_scl:0	scb[1].spi_mosi:1
P0.5	wco.wco_out			scb[1].uart_tx:0	scb[2].uart_tx:0	scb[1].i2c_sda:0	scb[1].spi_miso:1
P0.6			srss.ext_clk	scb[1].uart_cts:0	scb[2].uart_tx:1		scb[1].spi_clk:1
P0.7			tcpwm.line[0]:2	scb[1].uart_rts:0			scb[1].spi_select0:1
P1.0	ctb0_oa0+		tcpwm.line[2]:1	scb[0].uart_rx:1		scb[0].i2c_scl:0	scb[0].spi_mosi:1
P1.1	ctb0_oa0-		tcpwm.line_compl[2]:1	scb[0].uart_tx:1		scb[0].i2c_sda:0	scb[0].spi_miso:1
P1.2	ctb0_oa0_out		tcpwm.line[3]:1	scb[0].uart_cts:1	tcpwm.tr_in[2]	scb[2].i2c_scl:1	scb[0].spi_clk:1
P1.3	ctb0_oa1_out		tcpwm.line_compl[3]:1	scb[0].uart_rts:1	tcpwm.tr_in[3]	scb[2].i2c_sda:1	scb[0].spi_select0:1
P1.4	ctb0_oa1-						scb[0].spi_select1:1
P1.5	ctb0_oa1+						scb[0].spi_select2:1
P1.6	ctb0_oa0+						scb[0].spi_select3:1
P1.7	ctb0_oa1+ sar_ext_vref0 sar_ext_vref1						scb[2].spi_clk
P2.0	sarmux[0]	prgio[0].io[0]	tcpwm.line[4]:0	csd.comp	tcpwm.tr_in[4]	scb[1].i2c_scl:1	scb[1].spi_mosi:2
P2.1	sarmux[1]	prgio[0].io[1]	tcpwm.line_compl[4]:0		tcpwm.tr_in[5]	scb[1].i2c_sda:1	scb[1].spi_miso:2
P2.2	sarmux[2]	prgio[0].io[2]					scb[1].spi_clk:2
P2.3	sarmux[3]	prgio[0].io[3]					scb[1].spi_select0:2

Port/Pin	Analog	Smart I/O	Alternate Function 1	Alternate Function 2	Alternate Function 3	Deep Sleep 1	Deep Sleep 2
P2.4	sarmux[4]	prgio[0].io[4]	tcpwm.line[0]:1				scb[1].spi_select1:1
P2.5	sarmux[5]	prgio[0].io[5]	tcpwm.line_compl[0]:1				scb[1].spi_select2:1
P2.6	sarmux[6]	prgio[0].io[6]	tcpwm.line[1]:1				scb[1].spi_select3:1
P2.7	sarmux[7]	prgio[0].io[7]	tcpwm.line_compl[1]:1			lpcomp.comp[0]:1	scb[2].spi_mosi
P3.0		prgio[1].io[0]	tcpwm.line[0]:0	scb[1].uart_rx:1		scb[1].i2c_scl:2	scb[1].spi_miso:0
P3.1		prgio[1].io[1]	tcpwm.line_compl[0]:0	scb[1].uart_tx:1		scb[1].i2c_sda:2	scb[1].spi_miso:0
P3.2		prgio[1].io[2]	tcpwm.line[1]:0	scb[1].uart_cts:1		cpuss.swd_data	scb[1].spi_clk:0
P3.3		prgio[1].io[3]	tcpwm.line_compl[1]:0	scb[1].uart_rts:1		cpuss.swd_clk	scb[1].spi_select0:0
P3.4		prgio[1].io[4]	tcpwm.line[2]:0		tcpwm.tr_in[6]		scb[1].spi_select1:0
P3.5		prgio[1].io[5]	tcpwm.line_compl[2]:0				scb[1].spi_select2:0
P3.6		prgio[1].io[6]	tcpwm.line[3]:0				scb[1].spi_select3:0
P3.7		prgio[1].io[7]	tcpwm.line_compl[3]:0			lpcomp.comp[1]:1	scb[2].spi_miso
P4.0	csd.vref_ext			scb[0].uart_rx:0		scb[0].i2c_scl:1	scb[0].spi_mosi:0
P4.1	csd.cshieldpads			scb[0].uart_tx:0		scb[0].i2c_sda:1	scb[0].spi_miso:0
P4.2	csd.cmodpad			scb[0].uart_cts:0		lpcomp.comp[0]:0	scb[0].spi_clk:0
P4.3	csd.csh_tank			scb[0].uart_rts:0		lpcomp.comp[1]:0	scb[0].spi_select0:0

## Power

The following power system diagram shows the set of power supply pins as implemented for the PSoC 4100S. The system has one regulator in Active mode for the digital circuitry. There is no analog regulator; the analog circuits run directly from the  $V_{DD}$  input.

**Figure 4. Power Supply Connections**



There are two distinct modes of operation. In Mode 1, the supply voltage range is 1.8 V to 5.5 V (unregulated externally; internal regulator operational). In Mode 2, the supply range is 1.8 V  $\pm$ 5% (externally regulated; 1.71 to 1.89, internal regulator bypassed).

### Mode 1: 1.8 V to 5.5 V External Supply

In this mode, the PSoC 4100S is powered by an external power supply that can be anywhere in the range of 1.8 to 5.5 V. This range is also designed for battery-powered operation. For example, the chip can be powered from a battery system that starts at 3.5 V and works down to 1.8 V. In this mode, the internal regulator of the PSoC 4100S supplies the internal logic and its output is connected to the  $V_{CCD}$  pin. The  $V_{CCD}$  pin must be bypassed to ground via an external capacitor (0.1  $\mu$ F; X5R ceramic or better) and must not be connected to anything else.

### Mode 2: 1.8 V $\pm$ 5% External Supply

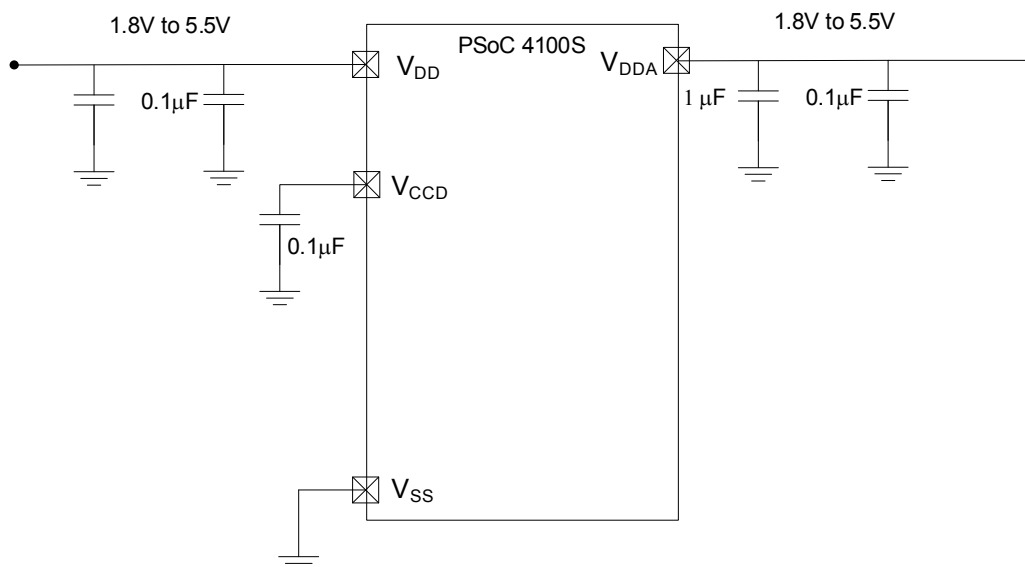
In this mode, the PSoC 4100S is powered by an external power supply that must be within the range of 1.71 to 1.89 V; note that this range needs to include the power supply ripple too. In this mode, the  $V_{DD}$  and  $V_{CCD}$  pins are shorted together and bypassed. The internal regulator can be disabled in the firmware.

Bypass capacitors must be used from  $V_{DDD}$  to ground. The typical practice for systems in this frequency range is to use a capacitor in the 1- $\mu$ F range, in parallel with a smaller capacitor (0.1  $\mu$ F, for example). Note that these are simply rules of thumb and that, for critical applications, the PCB layout, lead inductance, and the bypass capacitor parasitic should be simulated to design and obtain optimal bypassing.

An example of a bypass scheme is shown in the following diagram.

**Figure 5. External Supply Range from 1.8 V to 5.5 V with Internal Regulator Active**

Power supply bypass connections example





**Table 3. DC Specifications** (continued)

Typical values measured at  $V_{DD} = 3.3\text{ V}$  and  $25\text{ }^{\circ}\text{C}$ .

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
Sleep Mode, VDDD = 1.8 V to 5.5 V (Regulator on)							
SID22	IDD17	I <sup>2</sup> C wakeup WDT, and Comparators on	–	1.7	2.2	mA	6 MHZ. Max is at 85 °C and 5.5 V.
SID25	IDD20	I <sup>2</sup> C wakeup, WDT, and Comparators on.	–	2.2	2.5		12 MHZ. Max is at 85 °C and 5.5 V.
Sleep Mode, VDD = 1.71 V to 1.89 V (Regulator bypassed)							
SID28	IDD23	I <sup>2</sup> C wakeup, WDT, and Comparators on	–	0.7	0.9	mA	6 MHZ. Max is at 85 °C and 5.5 V.
SID28A	IDD23A	I <sup>2</sup> C wakeup, WDT, and Comparators on	–	1	1.2	mA	12 MHZ. Max is at 85 °C and 5.5 V.
Deep Sleep Mode, VDD = 1.8 V to 3.6 V (Regulator on)							
SID31	IDD26	I <sup>2</sup> C wakeup and WDT on	–	2.5	60	μA	Max is at 3.6 V and 85 °C.
Deep Sleep Mode, VDD = 3.6 V to 5.5 V (Regulator on)							
SID34	IDD29	I <sup>2</sup> C wakeup and WDT on	–	2.5	60	μA	Max is at 5.5 V and 85 °C.
Deep Sleep Mode, VDD = VCCD = 1.71 V to 1.89 V (Regulator bypassed)							
SID37	IDD32	I <sup>2</sup> C wakeup and WDT on	–	2.5	65	μA	Max is at 1.89 V and 85 °C.
XRES Current							
SID307	IDD_XR	Supply current while XRES asserted	–	2	5	mA	–

**Table 4. AC Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID48	F <sub>CPU</sub>	CPU frequency	DC	–	48	MHz	$1.71 \leq V_{DD} \leq 5.5$
SID49 <sup>[3]</sup>	T <sub>SLEEP</sub>	Wakeup from Sleep mode	–	0	–	μs	
SID50 <sup>[3]</sup>	T <sub>DEEPSLEEP</sub>	Wakeup from Deep Sleep mode	–	35	–		

**Note**

2. Guaranteed by characterization.



## GPIO

**Table 5. GPIO DC Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID57	$V_{IH}^{[3]}$	Input voltage high threshold	$0.7 \times V_{DDD}$	–	–	V	CMOS Input
SID58	$V_{IL}$	Input voltage low threshold	–	–	$0.3 \times V_{DDD}$		CMOS Input
SID241	$V_{IH}^{[3]}$	LVTTL input, $V_{DDD} < 2.7$ V	$0.7 \times V_{DDD}$	–	–		–
SID242	$V_{IL}$	LVTTL input, $V_{DDD} < 2.7$ V	–	–	$0.3 \times V_{DDD}$		–
SID243	$V_{IH}^{[3]}$	LVTTL input, $V_{DDD} \geq 2.7$ V	2.0	–	–		–
SID244	$V_{IL}$	LVTTL input, $V_{DDD} \geq 2.7$ V	–	–	0.8		–
SID59	$V_{OH}$	Output voltage high level	$V_{DDD} - 0.6$	–	–		$I_{OH} = 4$ mA at 3 V $V_{DDD}$
SID60	$V_{OH}$	Output voltage high level	$V_{DDD} - 0.5$	–	–		$I_{OH} = 1$ mA at 1.8 V $V_{DDD}$
SID61	$V_{OL}$	Output voltage low level	–	–	0.6		$I_{OL} = 4$ mA at 1.8 V $V_{DDD}$
SID62	$V_{OL}$	Output voltage low level	–	–	0.6		$I_{OL} = 10$ mA at 3 V $V_{DDD}$
SID62A	$V_{OL}$	Output voltage low level	–	–	0.4		$I_{OL} = 3$ mA at 3 V $V_{DDD}$
SID63	$R_{PULLUP}$	Pull-up resistor	3.5	5.6	8.5	k $\Omega$	–
SID64	$R_{PULLDOWN}$	Pull-down resistor	3.5	5.6	8.5		–
SID65	$I_{IL}$	Input leakage current (absolute value)	–	–	2	nA	25 °C, $V_{DDD} = 3.0$ V
SID66	$C_{IN}$	Input capacitance	–	–	7	pF	–
SID67 <sup>[4]</sup>	$V_{HYSTTL}$	Input hysteresis LVTTL	25	40	–	mV	$V_{DDD} \geq 2.7$ V
SID68 <sup>[4]</sup>	$V_{HYSCMOS}$	Input hysteresis CMOS	$0.05 \times V_{DDD}$	–	–		$V_{DD} < 4.5$ V
SID68A <sup>[4]</sup>	$V_{HYSCMOS5V5}$	Input hysteresis CMOS	200	–	–		$V_{DD} > 4.5$ V
SID69 <sup>[4]</sup>	$I_{DIODE}$	Current through protection diode to $V_{DD}/V_{SS}$	–	–	100	$\mu$ A	–
SID69A <sup>[4]</sup>	$I_{TOT\_GPIO}$	Maximum total source or sink chip current	–	–	200	mA	–

**Table 6. GPIO AC Specifications**

(Guaranteed by Characterization)

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID70	$T_{RISEF}$	Rise time in fast strong mode	2	–	12	ns	3.3 V $V_{DDD}$ , Load = 25 pF
SID71	$T_{FALLF}$	Fall time in fast strong mode	2	–	12		3.3 V $V_{DDD}$ , Load = 25 pF
SID72	$T_{RISES}$	Rise time in slow strong mode	10	–	60	–	3.3 V $V_{DDD}$ , Load = 25 pF

**Notes**

3.  $V_{IH}$  must not exceed  $V_{DDD} + 0.2$  V.
4. Guaranteed by characterization.

**Table 6. GPIO AC Specifications**

(Guaranteed by Characterization) (continued)

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID73	$T_{FALLS}$	Fall time in slow strong mode	10	–	60	–	3.3 V $V_{DD}$ , Load = 25 pF
SID74	$F_{GPIOOUT1}$	GPIO $F_{OUT}$ ; 3.3 V $\leq V_{DD} \leq 5.5$ V Fast strong mode	–	–	33	MHz	90/10%, 25 pF load, 60/40 duty cycle
SID75	$F_{GPIOOUT2}$	GPIO $F_{OUT}$ ; 1.71 V $\leq V_{DD} \leq 3.3$ V Fast strong mode	–	–	16.7		90/10%, 25 pF load, 60/40 duty cycle
SID76	$F_{GPIOOUT3}$	GPIO $F_{OUT}$ ; 3.3 V $\leq V_{DD} \leq 5.5$ V Slow strong mode	–	–	7		90/10%, 25 pF load, 60/40 duty cycle
SID245	$F_{GPIOOUT4}$	GPIO $F_{OUT}$ ; 1.71 V $\leq V_{DD} \leq 3.3$ V Slow strong mode.	–	–	3.5		90/10%, 25 pF load, 60/40 duty cycle
SID246	$F_{GPIOIN}$	GPIO input operating frequency; 1.71 V $\leq V_{DD} \leq 5.5$ V	–	–	48		90/10% $V_{IO}$

XRES

**Table 7. XRES DC Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID77	$V_{IH}$	Input voltage high threshold	$0.7 \times V_{DD}$	–	–	V	CMOS Input
SID78	$V_{IL}$	Input voltage low threshold	–	–	$0.3 \times V_{DD}$		
SID79	$R_{PULLUP}$	Pull-up resistor	–	60	–	k $\Omega$	–
SID80	$C_{IN}$	Input capacitance	–	–	7	pF	–
SID81 <sup>[5]</sup>	$V_{HYSXRES}$	Input voltage hysteresis	–	100	–	mV	Typical hysteresis is 200 mV for $V_{DD} > 4.5$ V
SID82	$I_{DIODE}$	Current through protection diode to $V_{DD}/V_{SS}$	–	–	100	$\mu$ A	

**Table 8. XRES AC Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID83 <sup>[5]</sup>	$T_{RESETWIDTH}$	Reset pulse width	1	–	–	$\mu$ s	–
BID194 <sup>[5]</sup>	$T_{RESETWAKE}$	Wake-up time from reset release	–	–	2.7	ms	–

**Note**

5. Guaranteed by characterization.

**Table 9. CTBm Opamp Specifications** *(continued)*

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
		General opamp specs for both internal and external modes					
SID281	V <sub>IN</sub>	Charge-pump on, V <sub>DDA</sub> = 2.7 V	−0.05	−	V <sub>DDA</sub> -0.2	V	−
SID282	V <sub>CM</sub>	Charge-pump on, V <sub>DDA</sub> = 2.7 V	−0.05	−	V <sub>DDA</sub> -0.2		−
	V <sub>OUT</sub>	V <sub>DDA</sub> = 2.7 V					
SID283	V <sub>OUT_1</sub>	power=hi, Iload=10 mA	0.5	−	V <sub>DDA</sub> -0.5	V	−
SID284	V <sub>OUT_2</sub>	power=hi, Iload=1 mA	0.2	−	V <sub>DDA</sub> -0.2		−
SID285	V <sub>OUT_3</sub>	power=med, Iload=1 mA	0.2	−	V <sub>DDA</sub> -0.2		−
SID286	V <sub>OUT_4</sub>	power=lo, Iload=0.1 mA	0.2	−	V <sub>DDA</sub> -0.2		−
SID288	V <sub>OS_TR</sub>	Offset voltage, trimmed	−1.0	±0.5	1.0	mV	High mode, input 0 V to V <sub>DDA</sub> -0.2 V
SID288A	V <sub>OS_TR</sub>	Offset voltage, trimmed	−	±1	−		Medium mode, input 0 V to V <sub>DDA</sub> -0.2 V
SID288B	V <sub>OS_TR</sub>	Offset voltage, trimmed	−	±2	−		Low mode, input 0 V to V <sub>DDA</sub> -0.2 V
SID290	V <sub>OS_DR_TR</sub>	Offset voltage drift, trimmed	−10	±3	10	µV/C	High mode
SID290A	V <sub>OS_DR_TR</sub>	Offset voltage drift, trimmed	−	±10	−	µV/C	Medium mode
SID290B	V <sub>OS_DR_TR</sub>	Offset voltage drift, trimmed	−	±10	−		Low mode
SID291	CMRR	DC	70	80	−	dB	Input is 0 V to V <sub>DDA</sub> -0.2 V, Output is 0.2 V to V <sub>DDA</sub> -0.2 V
SID292	PSRR	At 1 kHz, 10-mV ripple	70	85	−		V <sub>DDD</sub> = 3.6 V, high-power mode, input is 0.2 V to V <sub>DDA</sub> -0.2 V
	Noise						
SID294	VN2	Input-referred, 1 kHz, power=Hi	−	72	−	nV/rtHz	3
SID295	VN3	Input-referred, 10 kHz, power=Hi	−	28	−		Input and output are at 0.2 V to V <sub>DDA</sub> -0.2 V
SID296	VN4	Input-referred, 100 kHz, power=Hi	−	15	−		Input and output are at 0.2 V to V <sub>DDA</sub> -0.2 V
SID297	C <sub>LOAD</sub>	Stable up to max. load. Performance specs at 50 pF.	−	−	125	pF	−
SID298	SLEW_RATE	Cload = 50 pF, Power = High, V <sub>DDA</sub> = 2.7 V	6	−	−	V/µs	−

**Table 10. Comparator DC Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID84	V <sub>OFFSET1</sub>	Input offset voltage, Factory trim	–	–	±10	mV	
SID85	V <sub>OFFSET2</sub>	Input offset voltage, Custom trim	–	–	±4		
SID86	V <sub>HYST</sub>	Hysteresis when enabled	–	10	35		
SID87	V <sub>ICM1</sub>	Input common mode voltage in normal mode	0	–	V <sub>DDD</sub> -0.1	V	Modes 1 and 2
SID247	V <sub>ICM2</sub>	Input common mode voltage in low power mode	0	–	V <sub>DDD</sub>		
SID247A	V <sub>ICM3</sub>	Input common mode voltage in ultra low power mode	0	–	V <sub>DDD</sub> -1.15		V <sub>DDD</sub> ≥ 2.2 V at –40 °C
SID88	C <sub>MRR</sub>	Common mode rejection ratio	50	–	–	dB	V <sub>DDD</sub> ≥ 2.7V
SID88A	C <sub>MRR</sub>	Common mode rejection ratio	42	–	–		V <sub>DDD</sub> ≤ 2.7V
SID89	I <sub>CMP1</sub>	Block current, normal mode	–	–	400	μA	
SID248	I <sub>CMP2</sub>	Block current, low power mode	–	–	100		
SID259	I <sub>CMP3</sub>	Block current in ultra low-power mode	–	–	6		V <sub>DDD</sub> ≥ 2.2 V at –40 °C
SID90	Z <sub>CMP</sub>	DC Input impedance of comparator	35	–	–	MΩ	

**Table 11. Comparator AC Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID91	TRESP1	Response time, normal mode, 50 mV overdrive	–	38	110	ns	
SID258	TRESP2	Response time, low power mode, 50 mV overdrive	–	70	200		
SID92	TRESP3	Response time, ultra-low power mode, 200 mV overdrive	–	2.3	15	μs	V <sub>DDD</sub> ≥ 2.2 V at –40 °C

**Table 12. Temperature Sensor Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
SID93	TSENSACC	Temperature sensor accuracy	–5	±1	5	°C	–40 to +85 °C

**Table 13. SAR Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
<b>SAR ADC DC Specifications</b>							
SID94	A_RES	Resolution	–	–	12	bits	
SID95	A_CHNLS_S	Number of channels - single ended	–	–	16		
SID96	A-CHNKS_D	Number of channels - differential	–	–	4		Diff inputs use neighboring I/O
SID97	A-MONO	Monotonicity	–	–	–		Yes.
SID98	A_GAINERR	Gain error	–	–	±0.1	%	With external reference.

**Table 14. CSD and IDAC Specifications (continued)**

SPEC ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
SID315G	IDAC3CRT23	Output current of IDAC in 8-bit mode in medium range	69	–	82	µA	LSB = 300-nA typ.
SID315H	IDAC3CRT33	Output current of IDAC in 8-bit mode in high range	540	–	660	µA	LSB = 2.4-µA typ.
SID320	IDACOFFSET	All zeroes input	–	–	1	LSB	Polarity set by Source or Sink. Offset is 2 LSBs for 37.5 nA/LSB mode
SID321	IDACGAIN	Full-scale error less offset	–	–	±10	%	
SID322	IDACMISMATCH1	Mismatch between IDAC1 and IDAC2 in Low mode	–	–	9.2	LSB	LSB = 37.5-nA typ.
SID322A	IDACMISMATCH2	Mismatch between IDAC1 and IDAC2 in Medium mode	–	–	5.6	LSB	LSB = 300-nA typ.
SID322B	IDACMISMATCH3	Mismatch between IDAC1 and IDAC2 in High mode	–	–	6.8	LSB	LSB = 2.4-µA typ.
SID323	IDACSET8	Settling time to 0.5 LSB for 8-bit IDAC	–	–	10	µs	Full-scale transition. No external load.
SID324	IDACSET7	Settling time to 0.5 LSB for 7-bit IDAC	–	–	10	µs	Full-scale transition. No external load.
SID325	CMOD	External modulator capacitor.	–	2.2	–	nF	5-V rating, X7R or NP0 cap.

**Table 15. 10-bit CapSense ADC Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SIDA94	A_RES	Resolution	–	–	10	bits	Auto-zeroing is required every millisecond
SIDA95	A_CHNLS_S	Number of channels - single ended	–	–	16		Defined by AMUX Bus.
SIDA97	A-MONO	Monotonicity	–	–	–	Yes	
SIDA98	A_GAINERR	Gain error	–	–	±2	%	In $V_{REF}$ (2.4 V) mode with $V_{DDA}$ bypass capacitance of 10 µF
SIDA99	A_OFFSET	Input offset voltage	–	–	3	mV	In $V_{REF}$ (2.4 V) mode with $V_{DDA}$ bypass capacitance of 10 µF
SIDA100	A_ISAR	Current consumption	–	–	0.25	mA	
SIDA101	A_VINS	Input voltage range - single ended	$V_{SSA}$	–	$V_{DDA}$	V	
SIDA103	A_INRES	Input resistance	–	2.2	–	KΩ	
SIDA104	A_INCAP	Input capacitance	–	20	–	pF	
SIDA106	A_PSR	Power supply rejection ratio	–	60	–	dB	In $V_{REF}$ (2.4 V) mode with $V_{DDA}$ bypass capacitance of 10 µF
SIDA107	A_TACQ	Sample acquisition time	–	1	–	µs	
SIDA108	A_CONV8	Conversion time for 8-bit resolution at conversion rate = $F_{clk}/(2^{(N+2)})$ . Clock frequency = 48 MHz.	–	–	21.3	µs	Does not include acquisition time. Equivalent to 44.8 ksp/s including acquisition time.
SIDA108A	A_CONV10	Conversion time for 10-bit resolution at conversion rate = $F_{clk}/(2^{(N+2)})$ . Clock frequency = 48 MHz.	–	–	85.3	µs	Does not include acquisition time. Equivalent to 11.6 ksp/s including acquisition time.

**Table 21. UART DC Specifications<sup>[9]</sup>**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID160	I <sub>UART1</sub>	Block current consumption at 100 Kbps	–	–	55	μA	–
SID161	I <sub>UART2</sub>	Block current consumption at 1000 Kbps	–	–	312	μA	–

**Table 22. UART AC Specifications<sup>[9]</sup>**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID162	F <sub>UART</sub>	Bit rate	–	–	1	Mbps	–

**Table 23. LCD Direct Drive DC Specifications<sup>[9]</sup>**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID154	I <sub>LCDLOW</sub>	Operating current in low power mode	–	5	–	μA	16 × 4 small segment disp. at 50 Hz
SID155	C <sub>LDCAP</sub>	LCD capacitance per segment/common driver	–	500	5000	pF	–
SID156	LCD <sub>OFFSET</sub>	Long-term segment offset	–	20	–	mV	–
SID157	I <sub>LCDOP1</sub>	LCD system operating current V <sub>bias</sub> = 5 V	–	2	–	mA	32 × 4 segments. 50 Hz. 25 °C
SID158	I <sub>LCDOP2</sub>	LCD system operating current V <sub>bias</sub> = 3.3 V	–	2	–		32 × 4 segments. 50 Hz. 25 °C

**Table 24. LCD Direct Drive AC Specifications<sup>[9]</sup>**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID159	F <sub>LCD</sub>	LCD frame rate	10	50	150	Hz	–

**Note**

9. Guaranteed by characterization.

## SWD Interface

**Table 29. SWD Interface Specifications**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID213	F_SWDCCLK1	$3.3\text{ V} \leq V_{DD} \leq 5.5\text{ V}$	–	–	14	MHz	SWDCLK $\leq$ 1/3 CPU clock frequency
SID214	F_SWDCCLK2	$1.71\text{ V} \leq V_{DD} \leq 3.3\text{ V}$	–	–	7		SWDCLK $\leq$ 1/3 CPU clock frequency
SID215 <sup>[12]</sup>	T_SWDI_SETUP	$T = 1/f_{\text{SWDCLK}}$	$0.25 \cdot T$	–	–	ns	–
SID216 <sup>[12]</sup>	T_SWDI_HOLD	$T = 1/f_{\text{SWDCLK}}$	$0.25 \cdot T$	–	–		–
SID217 <sup>[12]</sup>	T_SWDO_VALID	$T = 1/f_{\text{SWDCLK}}$	–	–	$0.5 \cdot T$		–
SID217A <sup>[12]</sup>	T_SWDO_HOLD	$T = 1/f_{\text{SWDCLK}}$	1	–	–		–

## Internal Main Oscillator

**Table 30. IMO DC Specifications**

(Guaranteed by Design)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID218	I <sub>IMO1</sub>	IMO operating current at 48 MHz	–	–	250	μA	–
SID219	I <sub>IMO2</sub>	IMO operating current at 24 MHz	–	–	180	μA	–

**Table 31. IMO AC Specifications**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID223	F <sub>IMOTOL1</sub>	Frequency variation at 24, 32, and 48 MHz (trimmed)	–	–	±2	%	
SID226	T <sub>STARTIMO</sub>	IMO startup time	–	–	7	μs	–
SID228	T <sub>JITRMSIMO2</sub>	RMS jitter at 24 MHz	–	145	–	ps	–

## Internal Low-Speed Oscillator

**Table 32. ILO DC Specifications**

(Guaranteed by Design)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID231 <sup>[12]</sup>	I <sub>ILO1</sub>	ILO operating current	–	0.3	1.05	μA	–

**Table 33. ILO AC Specifications**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID234 <sup>[12]</sup>	T <sub>STARTILO1</sub>	ILO startup time	–	–	2	ms	–
SID236 <sup>[12]</sup>	T <sub>ILODUTY</sub>	ILO duty cycle	40	50	60	%	–
SID237	F <sub>ILOTRIM1</sub>	ILO frequency range	20	40	80	kHz	–

### Note

12. Guaranteed by characterization.



## Ordering Information

The marketing part numbers for the PSoC 4100S family are listed in the following table.

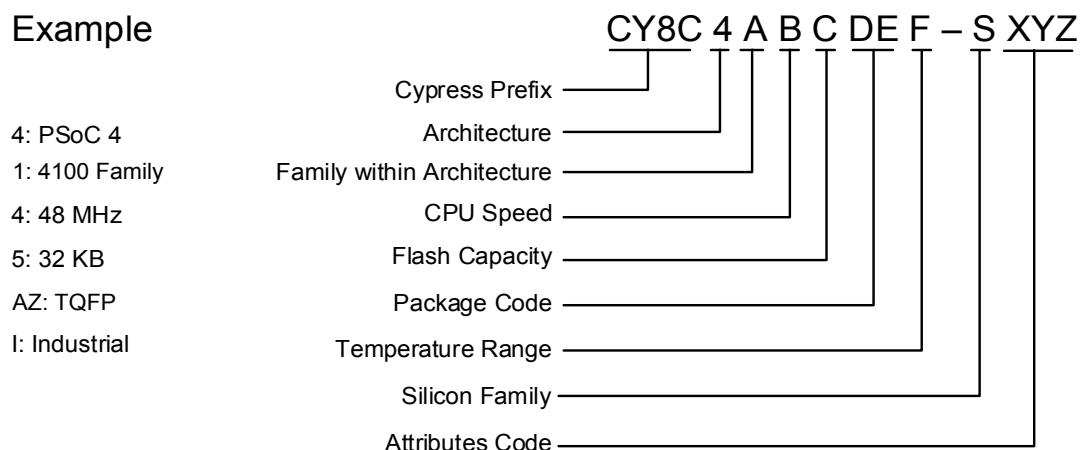
Category	MPN	Features													Package				
		Max CPU Speed (MHz)	Flash (KB)	SRAM (KB)	Opamp (CTBm)	CSD	10-bit CSD ADC	12-bit SAR ADC	ADC Sample Rate	LP Comparators	TCPWM Blocks	SCB Blocks	Smart I/Os	GPIO	35-WLCSP (0.35mm pitch)	32-QFN	40-QFN	48-TQFP	44-TQFP
4124	CY8C4124FNI-S403	24	16	4	2	0	1	0		2	5	2	8	31	X				
	CY8C4124FNI-S413	24	16	4	2	1	1	0		2	5	2	16	31	X				
	CY8C4124LQI-S412	24	16	4	2	1	1	0		2	5	2	16	27		X			
	CY8C4124LQI-S413	24	16	4	2	1	1	0		2	5	2	16	34			X		
	CY8C4124AZI-S413	24	16	4	2	1	1	0		2	5	2	16	36				X	
	CY8C4124FNI-S433	24	16	4	2	1	1	1	806 ksp/s	2	5	2	16	31	X				
	CY8C4124LQI-S432	24	16	4	2	1	1	1	806 ksp/s	2	5	2	16	27		X			
	CY8C4124LQI-S433	24	16	4	2	1	1	1	806 ksp/s	2	5	2	16	34			X		
4125	CY8C4124AZI-S433	24	16	4	2	1	1	1	806 ksp/s	2	5	2	16	36				X	
	CY8C4125FNI-S423	24	32	4	2	0	1	1	806 ksp/s	2	5	2	16	31	X				
	CY8C4125LQI-S422	24	32	4	2	0	1	1	806 ksp/s	2	5	2	16	27		X			
	CY8C4125LQI-S423	24	32	4	2	0	1	1	806 ksp/s	2	5	2	16	34			X		
	CY8C4125AZI-S423	24	32	4	2	0	1	1	806 ksp/s	2	5	2	16	36				X	
	CY8C4125AXI-S423	24	32	4	2	0	1	1	806 ksp/s	2	5	2	16	36					X
	CY8C4125FNI-S413	24	32	4	2	1	1	0		2	5	2	16	31	X				
	CY8C4125LQI-S412	24	32	4	2	1	1	0		2	5	2	16	27		X			
	CY8C4125LQI-S413	24	32	4	2	1	1	0		2	5	2	16	34			X		
	CY8C4125AZI-S413	24	32	4	2	1	1	0		2	5	2	16	36				X	
	CY8C4125FNI-S433	24	32	4	2	1	1	1	806 ksp/s	2	5	2	16	31	X				
	CY8C4125LQI-S432	24	32	4	2	1	1	1	806 ksp/s	2	5	2	16	27		X			
	CY8C4125LQI-S433	24	32	4	2	1	1	1	806 ksp/s	2	5	2	16	34			X		
	CY8C4125AZI-S433	24	32	4	2	1	1	1	806 ksp/s	2	5	2	16	36				X	
CY8C4125AXI-S433	24	32	4	2	1	1	1	806 ksp/s	2	5	2	16	36					X	
4126	CY8C4126AZI-S423	24	64	8	2	0	1	1	806 ksp/s	2	5	3	16	36				X	
	CY8C4126AXI-S423	24	64	8	2	0	1	1	806 ksp/s	2	5	3	16	36					X
	CY8C4126AZI-S433	24	64	8	2	1	1	1	806 ksp/s	2	5	3	16	36				X	
	CY8C4126AXI-S433	24	64	8	2	1	1	1	806 ksp/s	2	5	3	16	36					X
4145	CY8C4145AZI-S423	48	32	4	2	0	1	1	1 Msps	2	5	2	16	36				X	
	CY8C4145AXI-S423	48	32	4	2	0	1	1	1 Msps	2	5	2	16	36					X
	CY8C4145AXI-S433	48	32	4	2	1	1	1	1 Msps	2	5	2	16	36					X
4146	CY8C4146FNI-S423	48	64	8	2	0	1	1	1 Msps	2	5	3	16	31	X				
	CY8C4146LQI-S422	48	64	8	2	0	1	1	1 Msps	2	5	3	16	27		X			
	CY8C4146LQI-S423	48	64	8	2	0	1	1	1 Msps	2	5	3	16	34			X		
	CY8C4146AZI-S423	48	64	8	2	0	1	1	1 Msps	2	5	3	16	36				X	
	CY8C4146AXI-S423	48	64	8	2	0	1	1	1 Msps	2	5	3	16	36					X
	CY8C4146FNI-S433	48	64	8	2	1	1	1	1 Msps	2	5	3	16	31	X				
	CY8C4146LQI-S432	48	64	8	2	1	1	1	1 Msps	2	5	3	16	27		X			
	CY8C4146LQI-S433	48	64	8	2	1	1	1	1 Msps	2	5	3	16	34			X		
	CY8C4146AZI-S433	48	64	8	2	1	1	1	1 Msps	2	5	3	16	36				X	
CY8C4146AXI-S433	48	64	8	2	1	1	1	1 Msps	2	5	3	16	36					X	

The nomenclature used in the preceding table is based on the following part numbering convention:

Field	Description	Values	Meaning
CY8C	Cypress Prefix		
4	Architecture	4	PSoC 4
A	Family	1	4100 Family
B	CPU Speed	2	24 MHz
		4	48 MHz
C	Flash Capacity	4	16 KB
		5	32 KB
		6	64 KB
		7	128 KB
DE	Package Code	AX	TQFP (0.8mm pitch)
		AZ	TQFP (0.5mm pitch)
		LQ	QFN
		PV	SSOP
		FN	CSP
F	Temperature Range	I	Industrial
S	Silicon Family	S	PSoC 4A-S1, PSoC 4A-S2
		M	PSoC 4A-M
		L	PSoC 4A-L
		BL	PSoC 4A-BLE
XYZ	Attributes Code	000-999	Code of feature set in the specific family

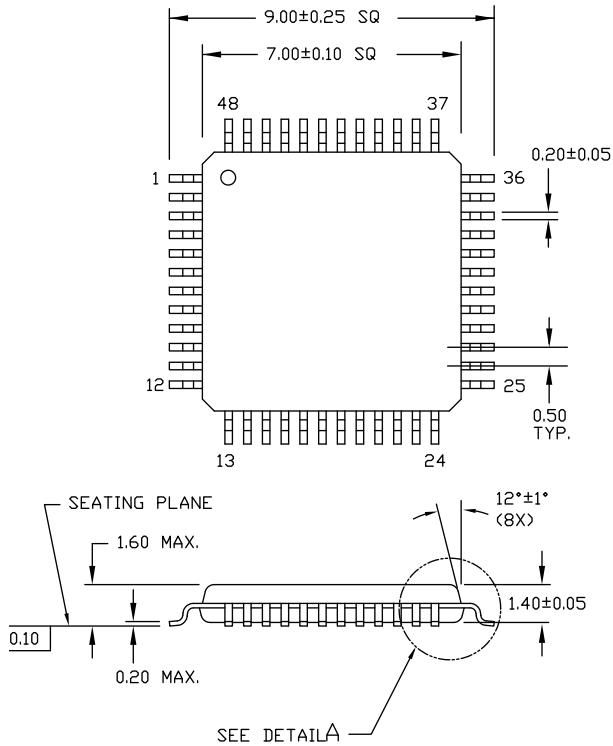
The following is an example of a part number:

## Example

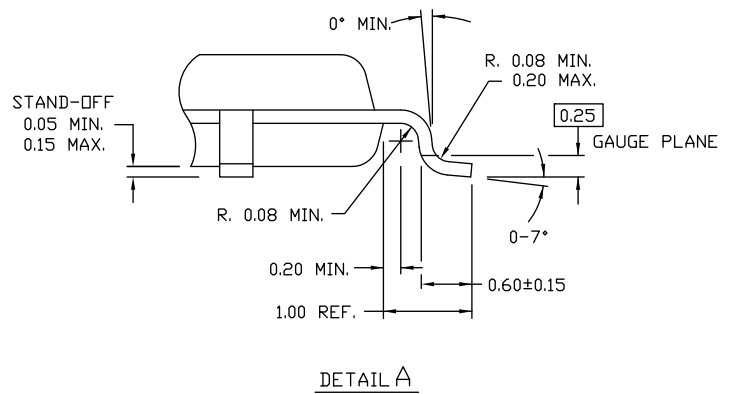


## Package Diagrams

**Figure 6. 48-pin TQFP Package Outline**

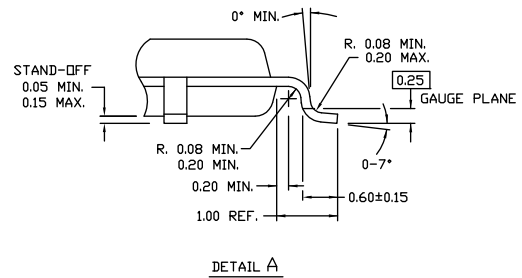
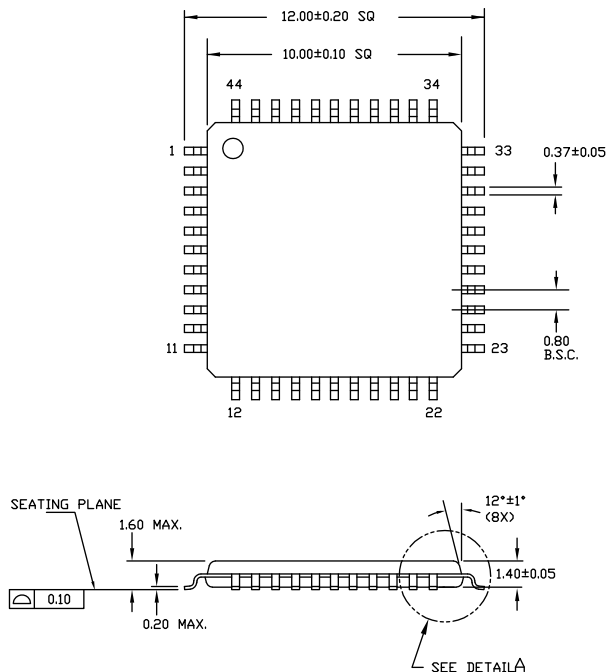


DIMENSIONS ARE IN MILLIMETERS



51-85135 \*C

**Figure 7. 44-pin TQFP Package Outline**

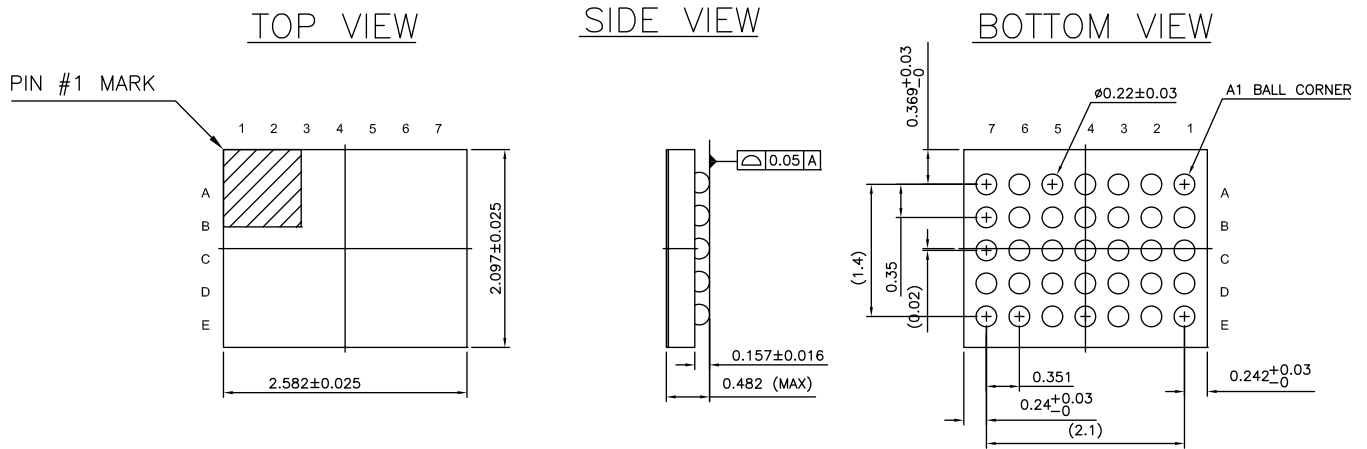


**NOTE:**

1. JEDEC STD REF MS-026
2. BODY LENGTH DIMENSION DOES NOT INCLUDE MOLD PROTRUSION/END FLASH  
MOLD PROTRUSION/END FLASH SHALL NOT EXCEED 0.0098 in (0.25 mm) PER SIDE  
BODY LENGTH DIMENSIONS ARE MAX PLASTIC BODY SIZE INCLUDING MOLD MISMATCH
3. DIMENSIONS IN MILLIMETERS

51-85064 \*G

**Figure 10. 35-Ball WLCSP Package Outline**



ALL DIMENSIONS ARE IN MM  
JEDEC Publication 95; Design Guide 4.18

002-09958 \*C

**Table 42. Acronyms Used in this Document** *(continued)*

Acronym	Description
PC	program counter
PCB	printed circuit board
PGA	programmable gain amplifier
PHUB	peripheral hub
PHY	physical layer
PICU	port interrupt control unit
PLA	programmable logic array
PLD	programmable logic device, see also PAL
PLL	phase-locked loop
PMDD	package material declaration data sheet
POR	power-on reset
PRES	precise power-on reset
PRS	pseudo random sequence
PS	port read data register
PSoC®	Programmable System-on-Chip™
PSRR	power supply rejection ratio
PWM	pulse-width modulator
RAM	random-access memory
RISC	reduced-instruction-set computing
RMS	root-mean-square
RTC	real-time clock
RTL	register transfer language
RTR	remote transmission request
RX	receive
SAR	successive approximation register
SC/CT	switched capacitor/continuous time
SCL	I <sup>2</sup> C serial clock
SDA	I <sup>2</sup> C serial data
S/H	sample and hold
SINAD	signal to noise and distortion ratio
SIO	special input/output, GPIO with advanced features. See GPIO.
SOC	start of conversion
SOF	start of frame
SPI	Serial Peripheral Interface, a communications protocol
SR	slew rate
SRAM	static random access memory
SRES	software reset
SWD	serial wire debug, a test protocol

**Table 42. Acronyms Used in this Document** *(continued)*

Acronym	Description
SWV	single-wire viewer
TD	transaction descriptor, see also DMA
THD	total harmonic distortion
TIA	transimpedance amplifier
TRM	technical reference manual
TTL	transistor-transistor logic
TX	transmit
UART	Universal Asynchronous Transmitter Receiver, a communications protocol
UDB	universal digital block
USB	Universal Serial Bus
USBIO	USB input/output, PSoC pins used to connect to a USB port
VDAC	voltage DAC, see also DAC, IDAC
WDT	watchdog timer
WOL	write once latch, see also NVL
WRES	watchdog timer reset
XRES	external reset I/O pin
XTAL	crystal

## Revision History

Description Title: PSoC® 4: PSoC 4100S Family Datasheet Programmable System-on-Chip (PSoC) Document Number: 002-00122				
Revision	ECN	Orig. of Change	Submission Date	Description of Change
**	4883809	WKA	08/28/2015	New datasheet
*A	4992376	WKA	10/30/2015	Updated <a href="#">Pinouts</a> . Added $V_{DDD} \geq 2.2V$ at $-40^{\circ}C$ under Conditions for specs SID247A, SID90, SID92. Updated <a href="#">Table 15</a> . Updated <a href="#">Ordering Information</a> .
*B	5037826	SLAN	12/08/2015	Changed datasheet status to Preliminary
*C	5060691	WKA	12/22/2015	Updated SCBs from 2 to 3. Updated SRAM size to 8 KB. Changed WLCSP package to 35-ball WLCSP. Updated Pin List and Alternate Pin Functions. Updated <a href="#">Ordering Information</a> .
*D	5139206	WKA	02/16/2016	Added Errata. Added 35 WLCSP package details. Updated $\theta_{JA}$ and $J_C$ values for all packages. Updated copyright information at the end of the document.
*E	5173961	WKA	03/15/2016	Updated values for SID79, BID194, SID175, and SID176. Updated <a href="#">CSD and IDAC Specifications</a> . Updated <a href="#">10-bit CapSense ADC Specifications</a> .
*F	5330930	WKA	07/27/2016	Updated <a href="#">CSD and IDAC Specifications</a> . Updated <a href="#">10-bit CapSense ADC Specifications</a> . Removed errata.
*G	5473409	WKA	10/13/2016	Added 44 TQFP pin and package details.
*H	5561833	WKA	01/09/2017	Updated <a href="#">Figure 3</a> . Changed PRGIO references to Smart I/O. Updated <a href="#">DC Specifications</a> . Updated <a href="#">Ordering Information</a> .